

**April 2009** 

## FGPF45N45T 450V, 45A PDP Trench IGBT

### **Features**

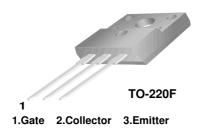
- · High Current Capability
- Low saturation voltage: V<sub>CE(sat)</sub> =1.6V @ I<sub>C</sub> = 45A
- · High input impedance
- · Fast switching

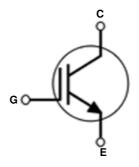
## **General Description**

Using Novel Trench IGBT Technology, Fairchild's new sesries of trench IGBTs offer the optimum performance for PDP applications where low conduction and switching losses are essential.

## **Applications**

PDP System





### **Absolute Maximum Ratings**

Symbol	Description		Ratings	Units		
V <sub>CES</sub>	Collector to Emitter Voltage		450	V		
V <sub>GES</sub>	Gate to Emitter Voltage		±30	V		
I <sub>CM (1)</sub>	Pulsed Collector Current	@ T <sub>C</sub> = 25°C	180	Α		
P <sub>D</sub>	Maximum Power Dissipation	$@ T_C = 25^{\circ}C$	51.6	W		
	Maximum Power Dissipation	$@ T_C = 100^{\circ}C$	20.6	W		
T <sub>J</sub>	Operating Junction Temperature		-55 to +150	°C		
T <sub>stg</sub>	Storage Temperature Range		Storage Temperature Range -55 to +150		-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C		

### Notes:

1: Repetitive test , Pulse width=100usec , Duty=0.1

### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units	
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	2.42	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	62.5	°C/W	

<sup>\*</sup> lc\_pluse limited by max Tj

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Eco Status	Packaging Type	Qty per Tube
FGPF45N45T	FGFP45N45TTU	TO-220F	RoHS	Rail / Tube	50ea



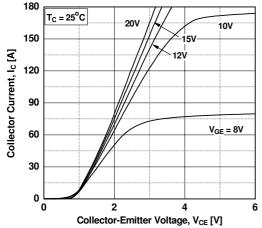
For Fairchild's definition of "green" Eco Status, please visit: <a href="http://www.fairchildsemi.com/company/green/rohs\_green.html">http://www.fairchildsemi.com/company/green/rohs\_green.html</a>.

# Electrical Characteristics of the IGBT $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Charac	teristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250\mu A$	450	-	-	V
$\Delta BV_CES \ \Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_C = 250\mu A$	-	0.5	-	V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	100	μΑ
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±400	nA
On Charac	teristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_{C} = 250 \mu A, V_{CE} = V_{GE}$	3.0	4.3	5.5	V
. ,		I <sub>C</sub> = 20A, V <sub>GE</sub> = 15V	-	1.21	1.5	V
	Collector to Emitter Saturation Voltage	I <sub>C</sub> = 45A, V <sub>GE</sub> = 15V	-	1.60	-	V
		I <sub>C</sub> = 45A, V <sub>GE</sub> = 15V, T <sub>C</sub> = 125°C	-	1.57	-	٧
Dynamic C	haracteristics		<u>"</u>			
C <sub>ies</sub>	Input Capacitance		-	2140	-	pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30V_{,} V_{GE} = 0V_{,}$ f = 1MHz	-	130	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	1 = 11VID2	-	102	-	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-	26	-	ns
t <sub>r</sub>	Rise Time	V 200V I 45A	-	100	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 200V, I_C = 45A,$ $R_G = 10\Omega, V_{GE} = 15V,$	-	170	-	ns
t <sub>f</sub>	Fall Time	Resistive Load, T <sub>C</sub> = 25°C	-	220	330	ns
t <sub>d(on)</sub>	Turn-On Delay Time		-	22	-	ns
t <sub>r</sub>	Rise Time	$V_{CC} = 200V, I_C = 45A,$ $R_G = 10\Omega, V_{GE} = 15V,$	-	90	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	132	-	ns
t <sub>f</sub>	Fall Time	Resistive Load, T <sub>C</sub> = 125°C	-	280	-	ns
Qg	Total Gate Charge		-	100	-	nC
Q <sub>ge</sub>	Gate to Emitter Charge	$V_{CE} = 200V, I_{C} = 45A,$ $V_{GE} = 15V$	-	15	-	nC
Q <sub>gc</sub>	Gate to Collector Charge	GE 101	-	46	-	nC

## **Typical Performance Characteristics**

Figure 1. Typical Output Characteristics



**Figure 2. Typical Output Characteristics** 

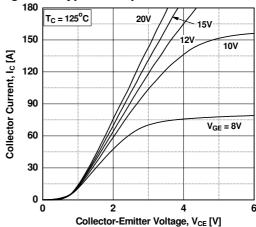


Figure 3. Typical Saturation Voltage Characteristics

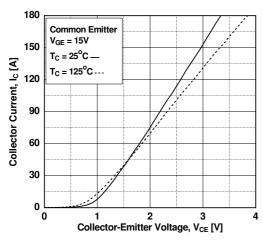


Figure 4. Transfer Characteristics

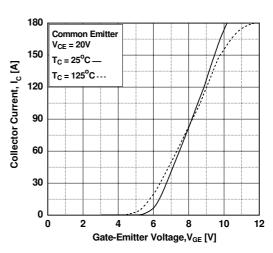


Figure 5. Saturation Voltage vs. Case **Temperature at Variant Current Level** 

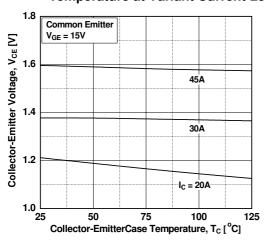
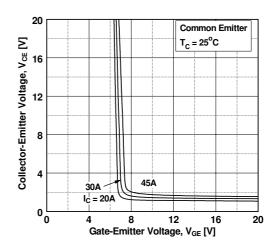


Figure 6. Saturation Voltage vs. V<sub>GE</sub>



## **Typical Performance Characteristics**

Figure 7. Saturation Voltage vs. V<sub>GE</sub>

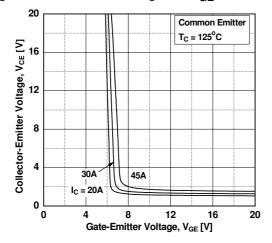


Figure 9. Gate charge Characteristics

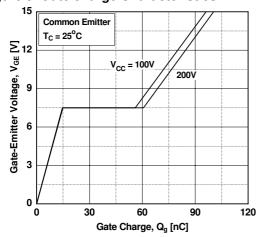
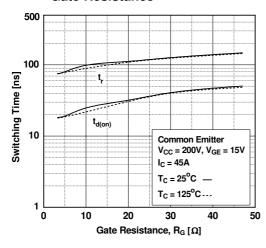


Figure 11. Turn-on Characteristics vs.
Gate Resistance



**Figure 8. Capacitance Characteristics** 

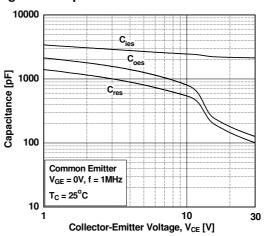


Figure 10. SOA Characteristics

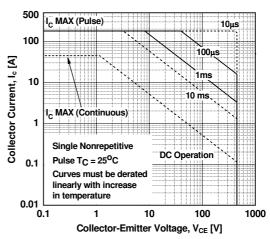
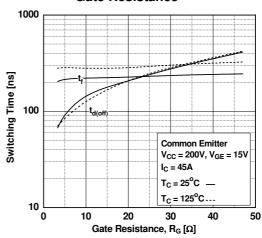


Figure 12. Turn-off Characteristics vs.
Gate Resistance



## **Typical Performance Characteristics**

Figure 13. Turn-on Characteristics vs. Collector Current

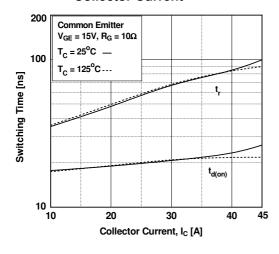


Figure 14. Turn-off Characteristics vs. Collector Current

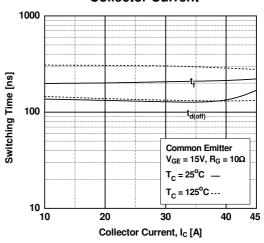


Figure 15. Switching Loss vs. Gate Resistance

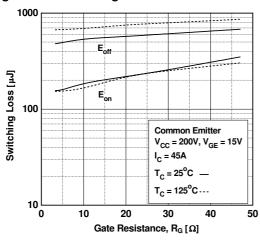


Figure 16. Switching Loss vs. Gate Resistance

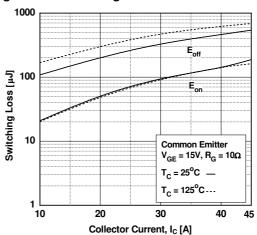
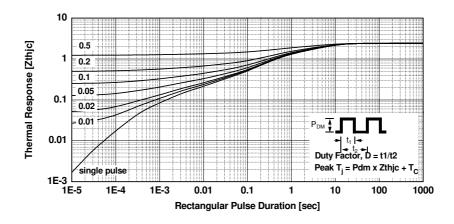
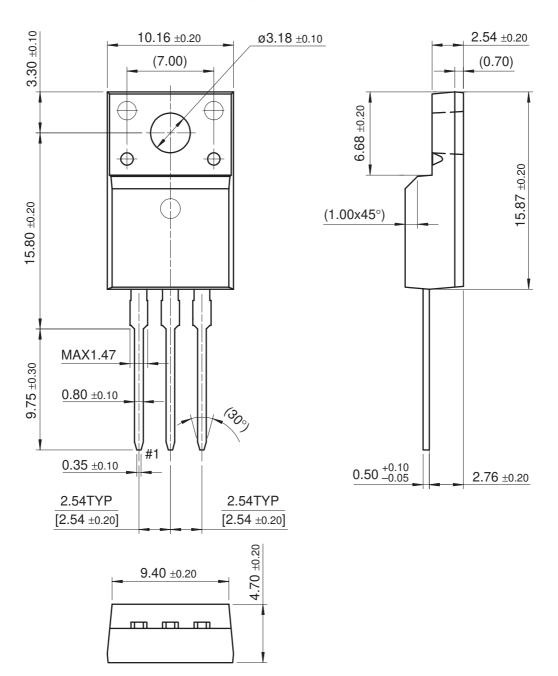


Figure 17. Transient Thermal Impedance of IGBT



## **Mechanical Dimensions**

# TO-220F



Dimensions in Millimeters





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